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To: **Technology Center 2800**  
**Attn: Vicki Short**

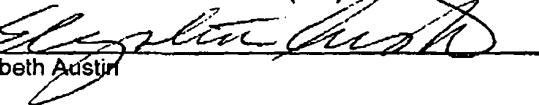
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NOTE: Ms. Short, per your request, attached is a copy of the Notice of Appeal that was mailed to the USPTO on August 12, 2003.

From: **Michael K. Skrehot**  
**Texas Instruments Incorporated**  
Facsimile: 972-917-4417  
Phone: 972-917-5653

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**In re the Application of: **Gonzalo Amador, et al.**Docket Number: **TI-30592**Serial No.: **09/817,694**Art Unit: **2823**Filed: **03/26/2001**Examiner: **Toledo, Fernando**For: **Fixture and Method for Uniform Electroless Metal Deposition on Integrated Circuit Bond Pads**Conf. No.: **9346****CERTIFICATION OF FACSIMILE TRANSMISSION**

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at (703) 746-8825 on the date shown below:

  
Elizabeth Austin  
Date**FACSIMILE COVER SHEET**

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NAME OF INVENTOR(S): <b>Gonzalo Amador, et al.</b>		RECEIPT DATE & SERIAL NO.: <b>09/817,694</b> FILING DATE: <b>03/26/2001</b>
TITLE OF INVENTION: <b>Fixture and Method for Uniform Electroless Metal Deposition on Integrated circuit Bond Pads</b>		
TI FILE NO.: <b>TI-30592</b> DEPOSIT ACCT. NO.: <b>20-0668</b>		
DATE FAXED: <b>October 28, 2003</b>		
DUE: <b>August 12, 2003</b>		
ATTY/SECY: <b>Michael Skrehot / E. Austin</b>		

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PO Box 655474, M/S 3999  
Dallas, TX 75265

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: **Gonzalo Amador, et al.** TI No.: **30592**  
 Serial No.: **09/817,694** Art Unit: **2823**  
 Filed: **03/26/2001** Examiner: **Toledo, Fernando**  
 For: **Fixture And Method For Uniform Electroless Metal Deposition On Integrated Circuit Bond Pads** Conf. No.: **9346**

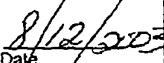
NOTICE OF APPEAL

Commissioner For Patents  
 Alexandria, VA 22313-1450

Sir:

Applicant hereby appeals to the Board of Appeals from the decision dated May 12, 2003, of the Primary Examiner finally rejecting Claims 1-5, 12, 16 and 17.

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

<u>MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)</u>	
I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450	
 Elizabeth Austin	 Date

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Respectfully submitted,



Michael K. Skrehot  
 Attorney for Applicant  
 Reg. No. 36,682

In The "Received" stamp of the Patent and Trademark Office imprinted hereon acknowledges the filing of:

<ul style="list-style-type: none"> <li><input type="checkbox"/> NEW APPLICATION TRANSMITTAL</li> <li><input type="checkbox"/> DECLARATION -</li> <li><input type="checkbox"/> ASSIGNMENT &amp; RECORDATION COVER SHEET</li> <li><input type="checkbox"/> FORMAL DRAWINGS ( SHEETS ENCLOSED )</li> <li><input type="checkbox"/> CONTINUATION APPLICATION</li> <li><input type="checkbox"/> DIVISIONAL APPLICATION</li> <li><input type="checkbox"/> ISSUE FEE &amp; LETTER OF TRANSMITTAL</li> </ul>	<ul style="list-style-type: none"> <li><input type="checkbox"/> AMENDMENT - _____ ( pages )</li> <li><input type="checkbox"/> AMENDMENT FEE TRANSMITTAL</li> <li><input type="checkbox"/> EOT - ____ MONTH(S)</li> <li><input checked="" type="checkbox"/> NOTICE OF APPEAL</li> <li><input type="checkbox"/> APPEAL BRIEF</li> <li><input type="checkbox"/> REPLY BRIEF ( IN TRIPPLICATE )</li> </ul>
<b>NAME OF INVENTOR(S):</b> Gonzalo Amador and Roger J. Stierman	
<b>TITLE OF INVENTION:</b> Fixture And Method For Uniform Electroless Metal Deposition On Integrated Circuit Bond Pads	
TI FILE NO.: TI-30592	DEPOSIT ACCT. NO.: 20-0668
<b>EXPRESS MAIL RECEIPT NO.:</b>  <b>MAILED DATE:</b> August 12, 2003 <b>DATE DUE:</b> August 12, 2003 <b>ATTY/SECY.:</b> Michael Skrehot / E. Austin	
SERIAL NUMBER: 09/817,694	
CONFIRMATION NO.: 9346	